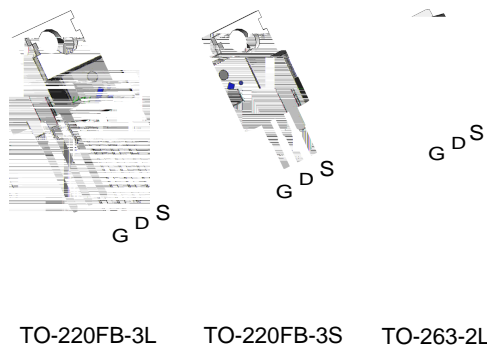


Feature

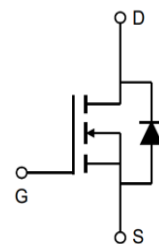
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Pin Description




Applications

-
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Ordering and Marking Information

	
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Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings °C			
	Junction Temperature Range		
Mounted on Large Heat Sink			
θ			
θ			

°C , .

Electrical Characteristics °C

Symbol	Parameter	Test Conditions	HY1904			Unit
			Min	Typ.	Max	
Static Characteristics						
		°C				
						m
						m
Diode Characteristics						

HY1904P/B/M

Electrical Characteristics (Cont.) °C

Symbol	Parameter	Test Conditions	HY1904			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
Gate Charge Characteristics						

Typical Operating Characteristics

Figure 1: Power Dissipation

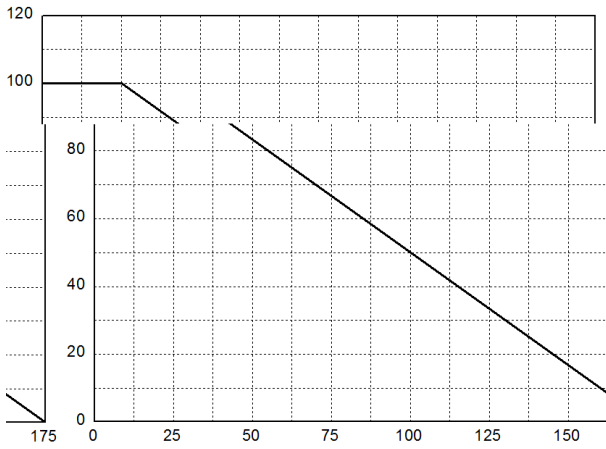


Figure 2: Drain Current

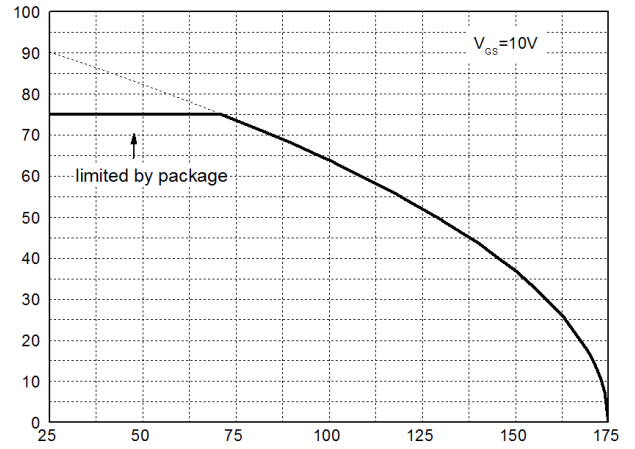


Figure 3: Safe Operation Area

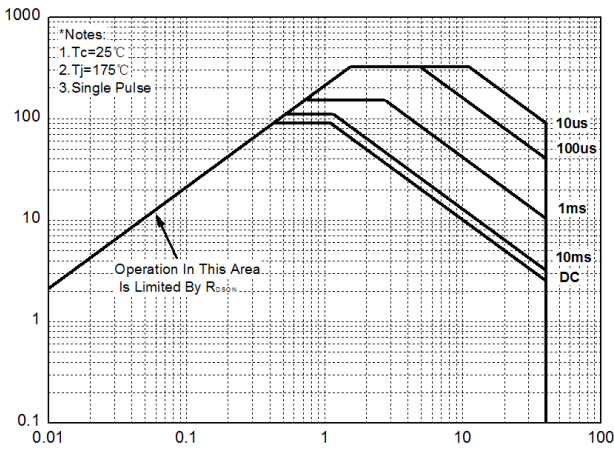


Figure 4: Thermal Transient Impedance

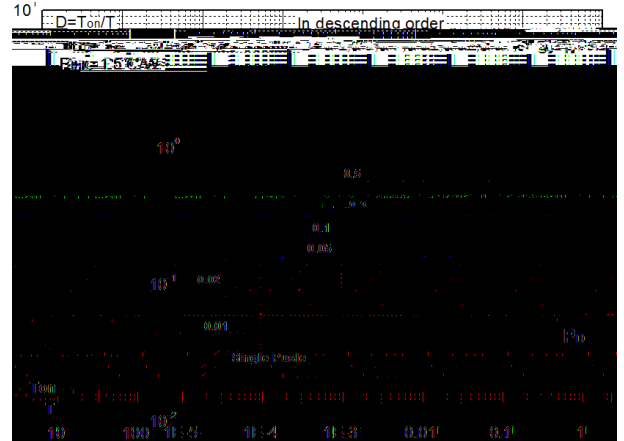


Figure 5: Output Characteristics

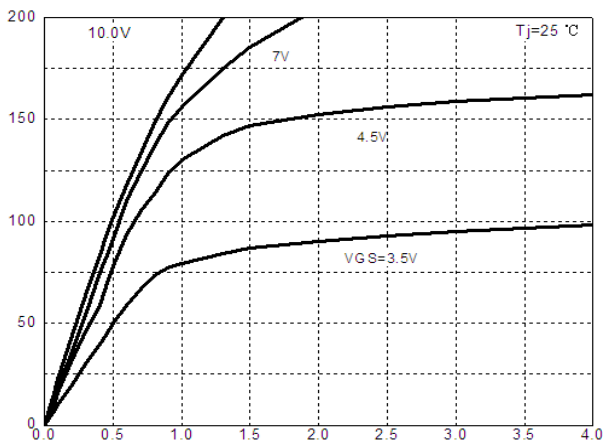
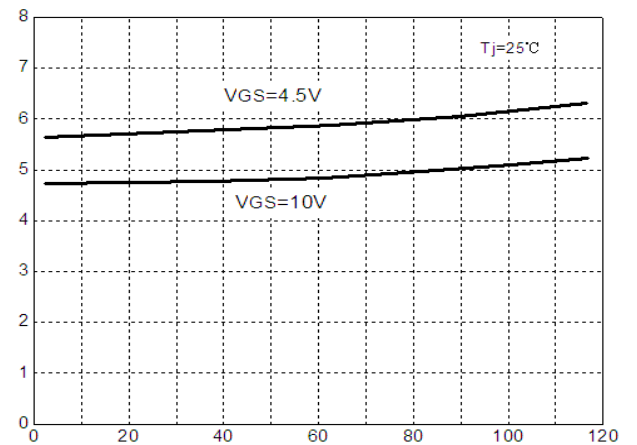


Figure 6: Drain-Source On Resistance



HY1904P/B/M

Typical Operating Characteristics(Cont.)

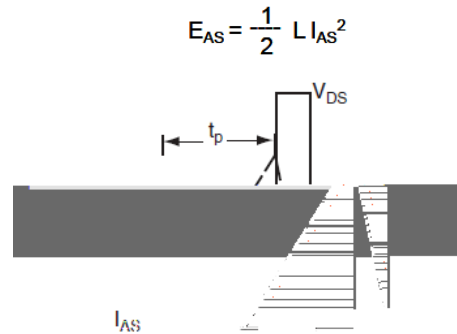
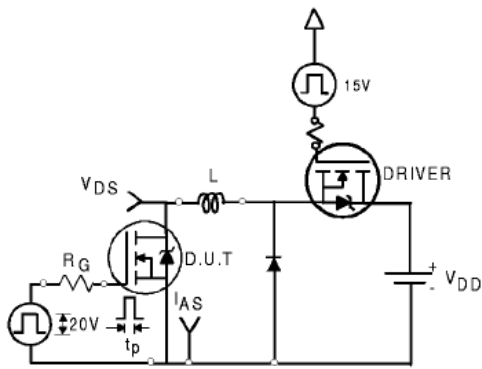
Figure 7: On-Resistance vs. Temperature

Figure 8: Source-Drain Diode Forward

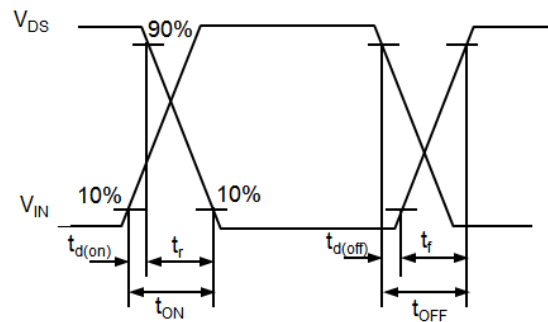
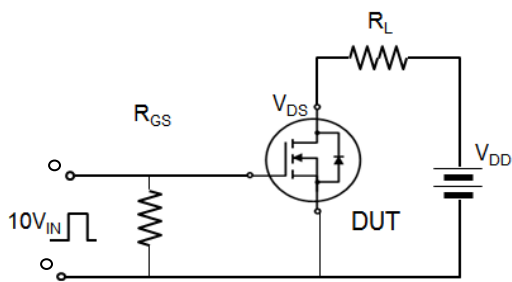
Figure 9: Capacitance Characteristics

Figure 10: Gate Charge Characteristics

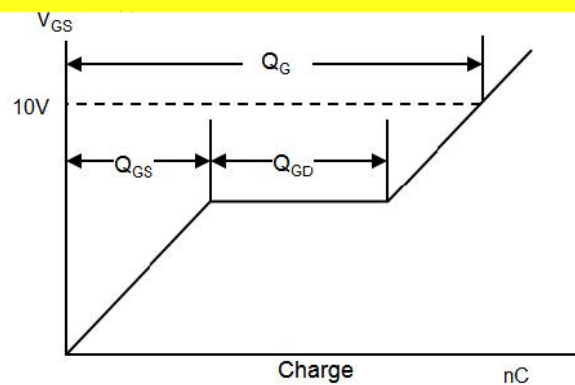
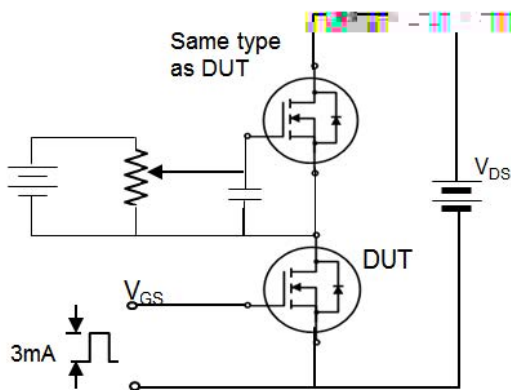
Avalanche Test Circuit



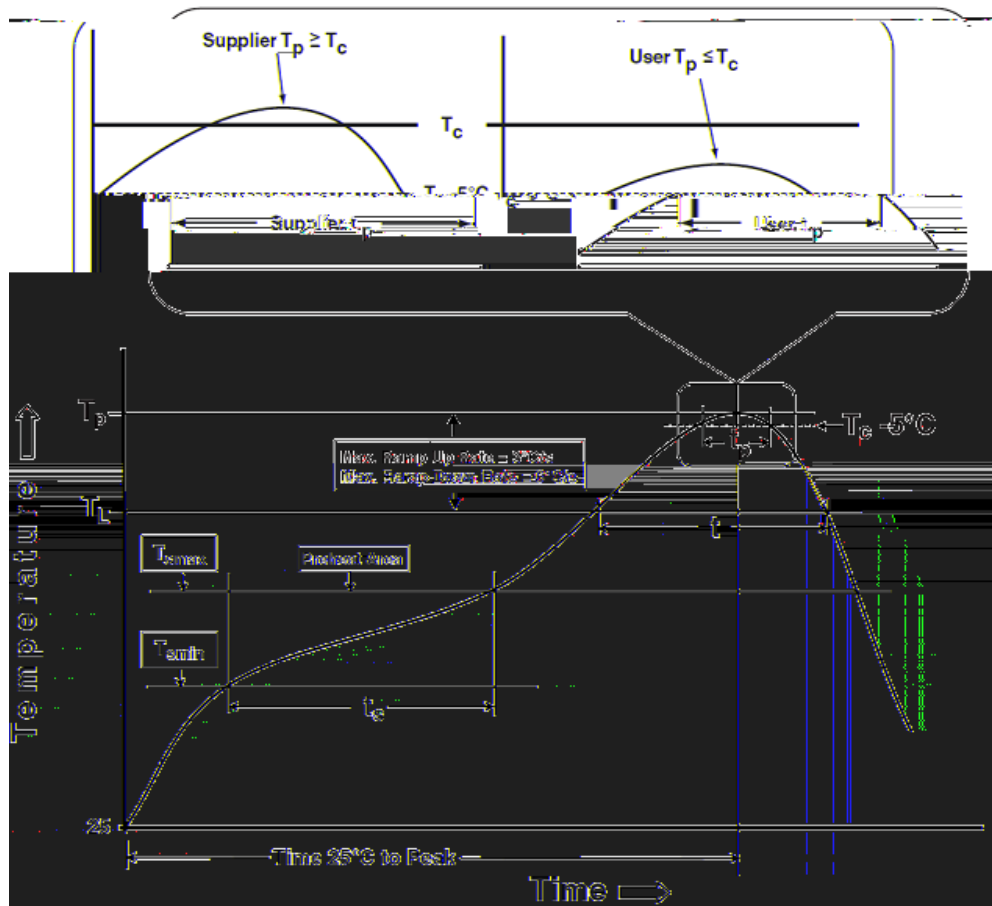
Switching Time Test Circuit



Gate Charge Test Circuit



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		

HY1904P/B/M

Package Thickness	Volume mm <350	Volume mm 350

Package Thickness	Volume mm <350	Volume mm 350-2000	Volume mm 2000
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